

CAN22C104KAGAC7210

CAN SMD Indust 250, Ceramic, 0.1 uF, 10%, COG, SMD Chip, MLCC, AC Rated, 2225, 3.2 mm



Click here for the 3D model.

| Dimensions | |
|------------|-----------------|
| Chip Size | 2225 |
| L | 5.6mm +/-0.4mm |
| W | 6.4mm +/-0.4mm |
| т | 2mm +/-0.20mm |
| S | 3.2mm MIN |
| В | 0.6mm +/-0.35mm |
| | |

Packaging Specifications

PackagingT&R, 330mm, Plastic TapePackaging Quantity2000

| General Information | |
|--------------------------|-----------------------------|
| Series | CAN SMD Indust 250 |
| Style | SMD Chip |
| Description | SMD Chip, MLCC, AC Rated |
| Features | Temperature Stable, Class I |
| RoHS | Yes |
| Termination | Tin |
| Marking | No |
| AEC-Q200 | No |
| Typical Component Weight | 370 mg |
| Shelf Life | 78 Weeks |
| MSL | 1 |

| Specifications | |
|--|---------------------|
| Capacitance | 0.1 uF |
| Measurement Condition | 1 kHz 1.0Vrms |
| Tolerance | 10% |
| Voltage AC | 250 VAC |
| Dielectric Withstanding Voltage | 945 VDC |
| Temperature Range | -55/+125°C |
| Temp. Coefficient | COG |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 15%, 1kHz 1.0Vrms |
| Dissipation Factor | 0.1% 1 kHz 1.0Vrms |
| Aging Rate | 0% Loss/Decade Hour |
| Insulation Resistance | 10 GOhms |

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